

REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Make change to 1.2.4 and power dissipation as specified under 1.3. - ro	99-06-09	R. MONNIN
B	Add appendix A. - ro	01-09-10	R. MONNIN
C	Add dose rate footnote under paragraph 1.5 and table I. Delete Neutron testing and Dose rate induced latchup testing. - ro	05-11-02	R. MONNIN
D	Add case outline X. Make changes to 1.2.4, 1.3 and figure 1. -rrp	09-03-09	R. HEBER
E	Delete figure 2, Radiation circuit and make change to paragraph 3.2.3. Delete references to device class M requirements. Update document paragraphs to current MIL-PRF-38535 requirements. - ro	16-06-02	C. SAFFLE



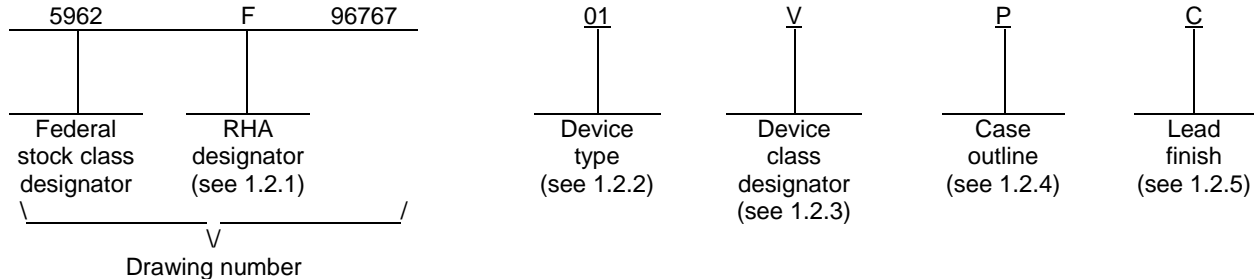
REV																				
SHEET																				
REV	E	E	E																	
SHEET	15	16	17																	
REV STATUS OF SHEETS	REV			E	E	E	E	E	E	E	E	E	E	E	E	E	E	E	E	
	SHEET			1	2	3	4	5	6	7	8	9	10	11	12	13	14			

PMIC N/A	PREPARED BY RICK OFFICER	<p align="center">DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990 http://www.landandmaritime.dla.mil</p>		
<p align="center">STANDARD MICROCIRCUIT DRAWING</p> <p>THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE</p> <p align="center">AMSC N/A</p>	CHECKED BY RAJESH PITHADIA			
	APPROVED BY MICHAEL FRYE	<p>MICROCIRCUIT, LINEAR, RADIATION HARDENED, HIGH SPEED, LOW POWER, CURRENT FEEDBACK AMPLIFIER WITH PROGRAMMABLE OUTPUT LIMITING, MONOLITHIC SILICON</p>		
	DRAWING APPROVAL DATE 96-02-21			
	REVISION LEVEL E	SIZE A	CAGE CODE 67268	5962-96767
SHEET 1 OF 17				

1. SCOPE

1.1 Scope. This drawing documents two product assurance class levels consisting of high reliability (device class Q) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.

1.2 PIN. The PIN is as shown in the following example:



1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	HS1135RH	Radiation hardened D.I., high speed, low power, current feedback amplifier with programmable output limiting

1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as follows:

<u>Device class</u>	<u>Device requirements documentation</u>
Q or V	Certification and qualification to MIL-PRF-38535

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
X	CDFP3-F14	14	Flat pack
P	GDIP1-T8 or CDIP2-T8	8	Dual-in-line

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 2

1.3 Absolute maximum ratings. ^{1/}

Voltage between +V _S and -V _S	12 V dc
Differential input voltage	5 V dc
Voltage at either input terminal	+V _S to -V _S
Output current	Short circuit protected ^{2/}
Output current (50% duty cycle)	60 mA ^{2/}
Maximum package power dissipation at T _A = +125°C (P _D):	
Case X	0.45 W ^{3/}
Case P	0.44 W ^{3/}
Junction temperature (T _J)	+175°C
Storage temperature range (T _{STG})	-65°C to +150°C
Lead temperature (soldering, 10 seconds)	+300°C
Thermal resistance, junction-to-case (θ _{JC}):	
Case X	25°C/W
Case P	30°C/W
Thermal resistance, junction-to-ambient (θ _{JA})	
Case X	115°C/W
Case P	110°C/W
Case P	115°C/W

1.4 Recommended operating conditions.

Operating supply voltage (±V _S)	±5 V
Load resistance (R _L)	≥ 50 Ω
Ambient operating temperature range (T _A)	-55°C to +125°C

1.5 Radiation features.

Maximum total dose available (dose rate = 50 – 300 rads(Si)/s)	300 krad (Si) ^{4/}
--	-----------------------------

- ^{1/} Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.
- ^{2/} Output is short circuit protected to ground. Brief short circuits to ground will not degrade reliability, however continuous (100% duty cycle) output current must not exceed 30 mA for maximum reliability.
- ^{3/} If device power exceeds package dissipation capability, provide heat sinking or derate linearly (the derating is based on θ_{JA}) at the following rate of 8.7 mW/°C for case outline P, or 9.1 mW/°C for case outline X.
- ^{4/} These parts may be dose rate sensitive in a space environment and may demonstrate enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions specified in MIL-STD-883, method 1019, condition A.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 3

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://quicksearch.dla.mil> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 as specified herein, or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

3.1.1 Microcircuit die. For the requirements of microcircuit die, see appendix A to this document.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V.

3.2.1 Case outline. The case outline shall be in accordance with 1.2.4 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.3 Radiation exposure circuit. The radiation exposure circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing and acquiring activity upon request.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535.

3.5.1 Certification/compliance mark. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 4

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ T _A ≤ +125°C V _S = ±5 V unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Input offset voltage	V _{IO}	V _{CM} = 0 V M,D,P,L,R,F <u>2/ 3/</u>	1	All	-5	5	mV
			2,3		-10	10	
			1		-10	10	
Common mode rejection ratio	CMRR	ΔV _{CM} = ±1.8 V, +V = 3.2 V, -V = -6.8 V, +V = 6.8 V, -V = -3.2 V	1	All	47		dB
			2		44		
		ΔV _{CM} = ±1.2 V, +V = 3.8 V, -V = -6.2 V, +V = 6.2 V, -V = -3.8 V M,D,P,L,R,F <u>2/ 3/</u>	3		44		
			1		44		
Power supply rejection ratio	PSRRP	ΔV _S = ±1.8 V, +V = 6.8 V, -V = -5 V, +V = 3.2 V, -V = -5 V	1	All	50		dB
			2		46		
		ΔV _S = ±1.2 V, +V = 6.2 V, -V = -5 V, +V = 3.8 V, -V = -5 V M,D,P,L,R,F <u>2/ 3/</u>	3		46		
			1		46		
	PSRRN	ΔV _S = ±1.8 V, +V = 5 V, -V = -6.8 V, +V = 5 V, -V = -3.2 V	1		50		
			2		46		
		ΔV _S = ±1.2 V, +V = 5 V, -V = -6.2, +V = 5 V, -V = -3.8 V M,D,P,L,R,F <u>2/ 3/</u>	3		46		
			1		46		
Non-inverting input (+IN) current	I _{BSP}	V _{CM} = 0 V M,D,P,L,R,F <u>2/ 3/</u>	1	All	-15	15	μA
			2,3		-25	25	
			1		-25	25	
+IN current common mode sensitivity	CMS _I BP	ΔV _{CM} = ±1.8 V, +V = 3.2 V, -V = -6.8 V, +V = 6.8 V, -V = -3.2 V	1	All		1.25	μA/V
			2			2.85	
		ΔV _{CM} = ±1.2 V, +V = 3.8 V, -V = -6.2, +V = 6.2 V, -V = -3.8 V M,D,P,L,R,F <u>2/ 3/</u>	3			2.85	
			1			2.85	
+IN resistance	+R _{IN}	<u>4/</u> M,D,P,L,R,F <u>2/ 3/</u>	1	All	800		kΩ
			2,3		350		
			1		350		

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 5

TABLE I. Electrical performance characteristics – Continued.

Test	Symbol	Conditions ^{1/} -55°C ≤ T _A ≤ +125°C V _S = ±5 V unless otherwise specified	Group A subgroups	Device type	Limits		Unit	
					Min	Max		
+IN current power supply sensitivity	PPSS _{IBP}	ΔV _S = ±1.8 V, +V = 6.8 V, -V = -5 V, +V = 3.2 V, -V = -5 V	1	All		1	μA/V	
			2			3		
		ΔV _S = ±1.2 V, +V = 6.2 V, -V = -5 V, +V = 3.8 V, -V = -5 V	3			3		
			M,D,P,L,R,F <u>2/ 3/</u>		1			3
	NPSS _{IBP}	ΔV _S = ±1.8 V, +V = 5 V, -V = -6.8 V, +V = 5 V, -V = -3.2 V	1			1		
			2			3		
		ΔV _S = ±1.2 V, +V = 5 V, -V = -6.2 V, +V = 5 V, -V = -3.8 V	3			3		
			M,D,P,L,R,F <u>2/ 3/</u>		1			3
Inverting input (-IN) current	I _{BSN}	V _{CM} = 0 V M,D,P,L,R,F <u>2/ 3/</u>	1	All	-7.5	7.5	μA	
			2,3			-25		25
			1			-25		25
-IN current common mode sensitivity	CMS _{IBN}	ΔV _{CM} = ±1.8 V, +V = 3.2 V, -V = -6.8 V, +V = 6.8 V, -V = -3.2 V	1	All		6	μA/V	
			2			8		
		ΔV _{CM} = ±1.2 V, +V = 3.8 V, -V = -6.2 V, +V = 6.2 V, -V = -3.8 V	3			8		
			M,D,P,L,R,F <u>2/ 3/</u>		1			8
-IN current power supply sensitivity	PPSS _{IBN}	ΔV _S = ±1.8 V, +V = 6.8 V, -V = -5 V, +V = 3.2 V, -V = -5 V	1	All		5	μA/V	
			2			8		
		ΔV _S = ±1.2 V, +V = 6.2 V, -V = -5 V, +V = 3.8 V, -V = -5 V	3			8		
			M,D,P,L,R,F <u>2/ 3/</u>		1			8
	NPSS _{IBN}	ΔV _S = ±1.8 V, +V = 5 V, -V = -6.8 V, +V = 5 V, -V = -3.2 V	1			5		
			2			8		
		ΔV _S = ±1.2 V, +V = 5 V, -V = -6.2 V, +V = 5 V, -V = -3.8 V	3			8		
			M,D,P,L,R,F <u>2/ 3/</u>		1			8

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 6

TABLE I. Electrical performance characteristics – Continued.

Test	Symbol	Conditions $\frac{1}{-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}}$ $V_S = \pm 5\text{ V}$ unless otherwise specified	Group A subgroups	Device type	Limits		Unit	
					Min	Max		
Output voltage swing	VOP100	$V_{IN} = -3.2\text{ V}, A_V = -1,$ $R_L = 100\ \Omega$	1	All	3		V	
		$V_{IN} = -3\text{ V}, A_V = -1,$ $R_L = 100\ \Omega$	2,3		2.8			
		$V_{IN} = -3\text{ V}, A_V = -1, \frac{2}{3}/$ $R_L = 100\ \Omega, \text{ M,D,P,L,R,F}$	1		2.8			
	VON100	$V_{IN} = +3.2\text{ V}, A_V = -1,$ $R_L = 100\ \Omega$	1					-3
		$V_{IN} = +3\text{ V}, A_V = -1,$ $R_L = 100\ \Omega$	2,3					-2.8
		$V_{IN} = +3\text{ V}, A_V = -1, \frac{2}{3}/$ $R_L = 100\ \Omega, \text{ M,D,P,L,R,F}$	1					-2.8
	VOP50	$V_{IN} = -2.7\text{ V}, A_V = -1,$ $R_L = 50\ \Omega$	1			2.5		
		$V_{IN} = -2.25\text{ V}, A_V = -1,$ $R_L = 50\ \Omega$	2			2.0		
		$V_{IN} = -2.25\text{ V}, A_V = -1,$ $R_L = 50\ \Omega$	3			1.4		
		$V_{IN} = -2.25\text{ V}, \frac{2}{3}/$ $A_V = -1, R_L = 50\ \Omega,$ M,D,P,L,R,F	1			1.4		
	VON50	$V_{IN} = +2.7\text{ V}, A_V = -1,$ $R_L = 50\ \Omega$	1					-2.5
		$V_{IN} = +2.25\text{ V}, A_V = -1,$ $R_L = 50\ \Omega$	2					-2.0
		$V_{IN} = +2.25\text{ V}, A_V = -1,$ $R_L = 50\ \Omega$	3					-1.4
		$V_{IN} = +2.25\text{ V}, \frac{2}{3}/$ $A_V = -1, R_L = 50\ \Omega,$ M,D,P,L,R,F	1					-1.4

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 7

TABLE I. Electrical performance characteristics – Continued.

Test	Symbol	Conditions ^{1/} -55°C ≤ T _A ≤ +125°C V _S = ±5 V unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Output current	+I _{OUT}	^{5/}	1	All	50		mA
			2		40		
			3		28		
			M,D,P,L,R,F ^{2/ 3/}		28		
	-I _{OUT}	^{5/}		1		-50	
				2		-40	
				3		-28	
				M,D,P,L,R,F ^{2/ 3/}		-28	
Quiescent power supply current	I _{CC}	R _L = 100 Ω	1	All	6.6	7.1	mA
			2,3		6.2	7.5	
			M,D,P,L,R,F ^{2/ 3/}		6.2	7.5	
	I _{EE}	R _L = 100 Ω	1		-6.6	-7.1	
			2,3		-6.2	-7.5	
			M,D,P,L,R,F ^{2/ 3/}		-6.2	-7.5	
Clamp accuracy	V _{HCLMP}	A _V = -1, V _{IN} = -2 V, V _H = 1 V	1	All	-125	125	mV
			2,3		-150	150	
			M,D,P,L,R,F ^{2/ 3/}		-150	150	
	V _{LCLMP}	A _V = -1, V _{OUT} = +2 V, V _L = -1 V	1		-125	125	
			2,3		-150	150	
			M,D,P,L,R,F ^{2/ 3/}		-150	150	
Input clamp current	V _{HBIAS}	V _H = 1 V	1,2,3	All		200	μA
			M,D,P,L,R,F ^{2/ 3/}		1		
	V _{LBIAS}	V _L = -1 V	1,2,3		-200		
			M,D,P,L,R,F ^{2/ 3/}	1		-200	

^{1/} Unless otherwise specified, A_V = +1, fixed resistance (R_F) = 510 Ω, source resistance (R_S) = 0 Ω, load resistance (R_L) = 100 Ω, and V_{OUT} = 0 V.

^{2/} Devices supplied by this drawing meet all levels M, D, P, L, R, and F of irradiation. However, this device is only tested at the "F" level. When performing post irradiation electrical measurements for any RHA level, T_A = +25°C.

^{3/} These parts may be dose rate sensitive in a space environment and may demonstrate enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions specified in MIL-STD-883, method 1019, condition A.

^{4/} Guaranteed from +IN common mode rejection test, by: +R_{IN} = 1/CMS_{IBP}.

^{5/} Guaranteed from V_{OUT} test with R_L = 50 Ω, by: I_{OUT} = V_{OUT}/50 Ω.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 8

Device type	01	
Case outline	X	P
Terminal number	Terminal symbol	
1	NC	NC
2	NC	-INPUT
3	-INPUT	+INPUT
4	+INPUT	-V _S
5	NC	V _L
6	NC	OUTPUT
7	-V _S	+V _S
8	NC	V _H
9	NC	----
10	V _L	----
11	OUTPUT	----
12	+V _S	----
13	V _H	----
14	NC	----

FIGURE 1. Terminal connections.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 9

3.6 Certificate of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein.

3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 shall be provided with each lot of microcircuits delivered to this drawing.

4. VERIFICATION

4.1 Sampling and inspection. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection.

4.2.1 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections, and as specified herein.

4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 4, 5, 6, 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 10

TABLE IIA. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	1
Final electrical parameters (see 4.2)	1,2,3 <u>1/</u>	1,2,3, <u>2/ 3/</u>
Group A test requirements (see 4.4)	1,2,3	1,2,3
Group C end-point electrical parameters (see 4.4)	1	1,2,3 <u>3/</u>
Group D end-point electrical parameters (see 4.4)	1	1
Group E end-point electrical parameters (see 4.4)	1	1

1/ PDA applies to subgroup 1.

2/ PDA applies to subgroups 1 and Δ.

3/ Delta limits as specified in table IIB shall be required where specified, and the delta limits shall be completed with reference to the zero hour electrical parameters (see Table I).

TABLE IIB. Burn-in and operating life test delta parameters. $T_A = +25^\circ\text{C}$.

Parameter	Symbol	Delta limits
Input offset voltage	V_{IO}	$\pm 3.0 \text{ mV}$
Positive input bias current	$+I_{IB}$	$\pm 6 \mu\text{A}$
Negative input bias current	$-I_{IB}$	$\pm 3 \mu\text{A}$

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table IIA herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at $T_A = +25^\circ\text{C} \pm 5^\circ\text{C}$, after exposure, to the subgroups specified in table IIA herein.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 11

4.4.4.1 Total dose irradiation testing. Total dose irradiation testing shall be performed in accordance with MIL-STD-883 method 1019, condition A and as specified herein.

4.4.4.1.1 Accelerated annealing test. Accelerated annealing tests shall be performed on all devices requiring a RHA level greater than 5 krads(Si). The post-anneal end-point electrical parameter limits shall be as specified in table I herein and shall be the pre-irradiation end-point electrical parameter limit at 25°C ±5°C. Testing shall be performed at initial qualification and after any design or process changes which may affect the RHA response of the device.

4.4.4.2 Dose rate burnout. When required by the customer, test shall be performed on devices, SEC, or approved test structures at technology qualifications and after any design or process changes which may effect the RHA capability of the process. Dose rate burnout shall be performed in accordance with test method 1023 of MIL-STD-883 and as specified herein.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-8108.

6.4 Comments. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in MIL-HDBK-103 and QML-38535. The vendors listed in MIL-HDBK-103 and QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.

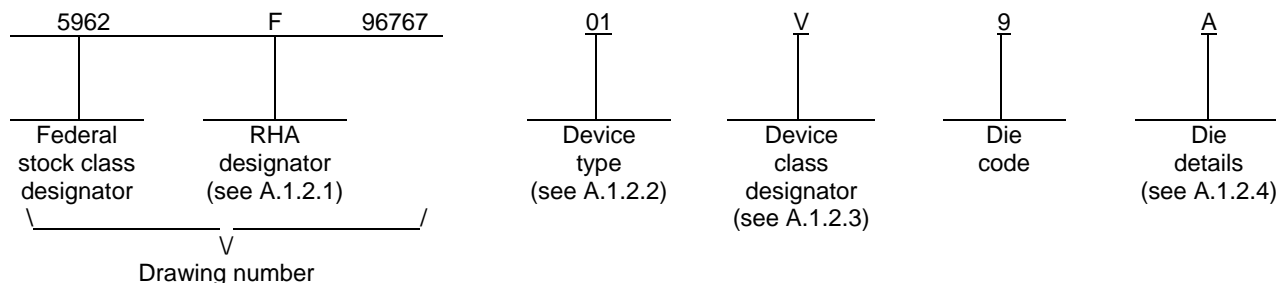
STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 12

APPENDIX A
APPENDIX A FORMS A PART OF SMD 5962-96767

A.1 SCOPE

A.1.1 Scope. This appendix establishes minimum requirements for microcircuit die to be supplied under the Qualified Manufacturers List (QML) Program. QML microcircuit die meeting the requirements of MIL-PRF-38535 and the manufacturers approved QM plan for use in monolithic microcircuits, multi-chip modules (MCMs), hybrids, electronic modules, or devices using chip and wire designs in accordance with MIL-PRF-38534 are specified herein. Two product assurance classes consisting of military high reliability (device class Q) and space application (device class V) are reflected in the Part or Identification Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.

A.1.2 PIN. The PIN is as shown in the following example:



A.1.2.1 RHA designator. Device classes Q and V RHA identified die meet the MIL-PRF-38535 specified RHA levels. A dash (-) indicates a non-RHA die.

A.1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	HS1135RH	Radiation hardened D.I., high speed, low power, current feedback amplifier with programmable output limiting

A.1.2.3 Device class designator.

<u>Device class</u>	<u>Device requirements documentation</u>
Q or V	Certification and qualification to the die requirements of MIL-PRF-38535

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A	5962-96767
	REVISION LEVEL E	SHEET 13

APPENDIX A
APPENDIX A FORMS A PART OF SMD 5962-96767

A.1.2.4 Die details. The die details designation is a unique letter which designates the die's physical dimensions, bonding pad location(s) and related electrical function(s), interface materials, and other assembly related information, for each product and variant supplied to this appendix.

A.1.2.4.1 Die physical dimensions.

<u>Die type</u>	<u>Figure number</u>
01	A-1

A.1.2.4.2 Die bonding pad locations and electrical functions.

<u>Die type</u>	<u>Figure number</u>
01	A-1

A.1.2.4.3 Interface materials.

<u>Die type</u>	<u>Figure number</u>
01	A-1

A.1.2.4.4 Assembly related information.

<u>Die type</u>	<u>Figure number</u>
01	A-1

A.1.3 Absolute maximum ratings. See paragraph 1.3 herein for details.

A.1.4 Recommended operating conditions. See paragraph 1.4 herein for details.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 14

APPENDIX A
APPENDIX A FORMS A PART OF SMD 5962-96767

A.2 APPLICABLE DOCUMENTS.

A.2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARD

MIL-STD-883 - Test Method Standard Microcircuits.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://quicksearch.dla.mil> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

A.2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

A.3 REQUIREMENTS

A.3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

A.3.2 Design, construction and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein and the manufacturer's QM plan for device classes Q and V.

A.3.2.1 Die physical dimensions. The die physical dimensions shall be as specified in A.1.2.4.1 and on figure A-1.

A.3.2.2 Die bonding pad locations and electrical functions. The die bonding pad locations and electrical functions shall be as specified in A.1.2.4.2 and on figure A-1.

A.3.2.3 Interface materials. The interface materials for the die shall be as specified in A.1.2.4.3 and on figure A-1.

A.3.2.4 Assembly related information. The assembly related information shall be as specified in A.1.2.4.4 and on figure A-1.

A.3.2.5 Radiation exposure circuit. The radiation exposure circuit shall be as defined in paragraph 3.2.3 herein.

A.3.3 Electrical performance characteristics and post-irradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and post-irradiation parameter limits are as specified in table I of the body of this document.

A.3.4 Electrical test requirements. The wafer probe test requirements shall include functional and parametric testing sufficient to make the packaged die capable of meeting the electrical performance requirements in table I.

A.3.5 Marking. As a minimum, each unique lot of die, loaded in single or multiple stack of carriers, for shipment to a customer, shall be identified with the wafer lot number, the certification mark, the manufacturer's identification and the PIN listed in A.1.2 herein. The certification mark shall be a "QML" or "Q" as required by MIL-PRF-38535.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 15

APPENDIX A
APPENDIX A FORMS A PART OF SMD 5962-96767

A.3.6 Certification of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see A.6.4 herein). The certificate of compliance submitted to DLA Land and Maritime -VA prior to listing as an approved source of supply for this appendix shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and the requirements herein.

A.3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 shall be provided with each lot of microcircuit die delivered to this drawing.

A.4 VERIFICATION

A.4.1 Sampling and inspection. For device classes Q and V, die sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modifications in the QM plan shall not affect the form, fit, or function as described herein.

A.4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and as defined in the manufacturer's QM plan. As a minimum, it shall consist of:

- a. Wafer lot acceptance for class V product using the criteria defined in MIL-STD-883, method 5007.
- b. 100% wafer probe (see paragraph A.3.4 herein).
- c. 100% internal visual inspection to the applicable class Q or V criteria defined in MIL-STD-883, method 2010 or the alternate procedures allowed in MIL-STD-883, method 5004.

A.4.3 Conformance inspection.

A.4.3.1 Group E inspection. Group E inspection is required only for parts intended to be identified as radiation assured (see A.3.5 herein). RHA levels for device classes Q and V shall be as specified in MIL-PRF-38535. End point electrical testing of packaged die shall be as specified in table IIA herein. Group E tests and conditions are as specified in paragraphs 4.4.4, 4.4.4.1, 4.4.4.1.1, and 4.4.4.2 herein.

A.5 DIE CARRIER

A.5.1 Die carrier requirements. The requirements for the die carrier shall be accordance with the manufacturer's QM plan or as specified in the purchase order by the acquiring activity. The die carrier shall provide adequate physical, mechanical and electrostatic protection.

A.6 NOTES

A.6.1 Intended use. Microcircuit die conforming to this drawing are intended for use in microcircuits built in accordance with MIL-PRF-38535 or MIL-PRF-38534 for government microcircuit applications (original equipment), design applications, and logistics purposes.

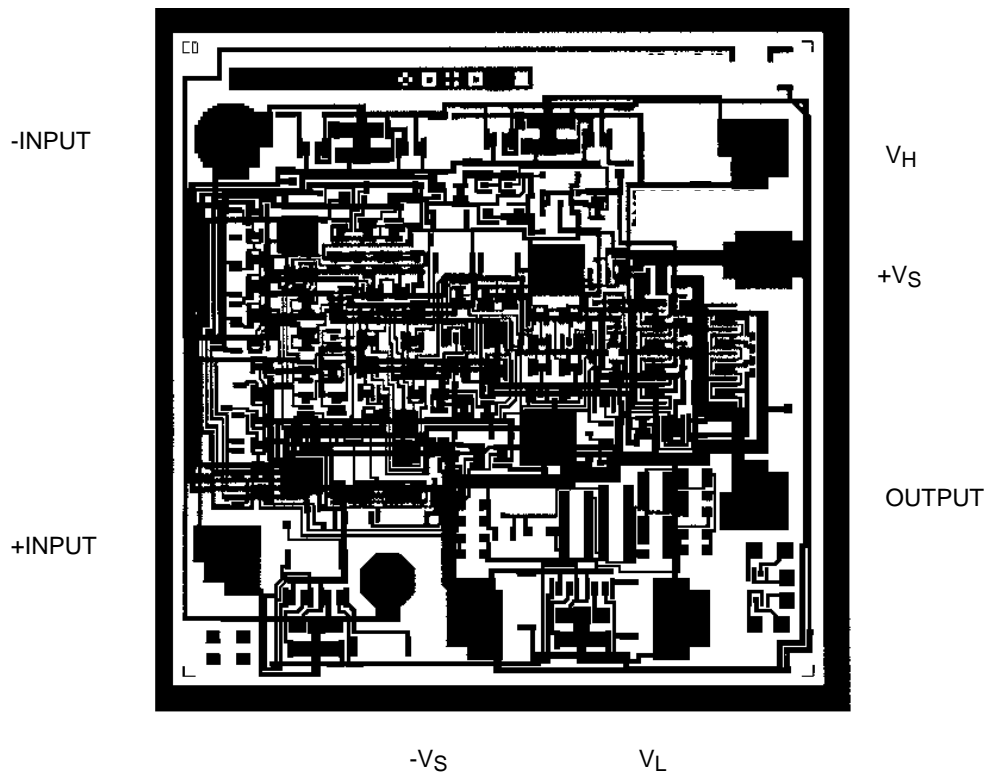
A.6.2 Comments. Comments on this appendix should be directed to DLA Land and Maritime -VA, Columbus, Ohio, 43218-3990 or telephone (614)-692-0540.

A.6.3 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

A.6.4 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in MIL-HDBK-103 and QML-38535. The vendors listed within MIL-HDBK-103 and QML-38535 have submitted a certificate of compliance (see A.3.6 herein) to DLA Land and Maritime -VA and have agreed to this drawing.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 16

APPENDIX A
 APPENDIX A FORMS A PART OF SMD 5962-96767



Die bonding pad locations and electrical functions

Die physical dimensions.

Die size: 1500 microns x 1500 microns

Die thickness: 14 mils \pm 1 mils

Interface materials.

Top metallization:

Metal 1: Al Cu (2%) / TiW 8.0 kÅ \pm 0.4 kÅ

Metal 2: AlCu 16.0 kÅ \pm 0.8 kÅ

Backside metallization: None

Glassivation.

Type: Nitride

Thickness: 4.0 kÅ \pm 0.5 kÅ

Substrate: UHF-1. Bonded wafer. Dielectric Isolation (DI)

Assembly related information.

Substrate potential: Floating

Special assembly instructions: None

FIGURE A-1. Die bonding pad locations and electrical functions.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-96767
		REVISION LEVEL E	SHEET 17

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 16-06-02

Approved sources of supply for SMD 5962-96767 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at <http://www.landandmaritime.dla.mil/Programs/Smcr/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962F9676701VPA	<u>3/</u>	HS7-1135RH-Q
5962F9676701VXC	34371	HS9-1135RH-Q
5962F9676701VPC	34371	HS7B-1135RH-Q
5962F9676701V9A	34371	HS0-1135RH-Q

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

Vendor CAGE
number

34371

Vendor name
and address

Intersil Corporation
1650 Robert J. Conlan Blvd. NE
Palm Bay, FL 32905-3406

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.